

描述 / Descriptions

2.0A 表面贴装玻璃钝化整流桥，薄型 ABF 封装。
2.0A Surface Mount Glass Passivated Bridge Rectifier, ABF thin package.

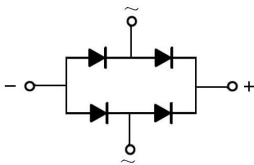
特征 / Features

玻璃钝化芯片，反向电压：1000V，正向电流：2.0A，快速反向恢复时间，适用于表面贴装。无卤产品。
Glass Passivated Chip Junction, Reverse Voltage: 1000V, Forward Current: 2.0A, Fast reverse recovery time, Designed for Surface Mount Application. Halogen free product.

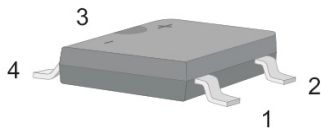
用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit

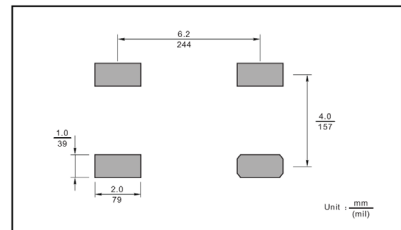


引脚排列 / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

The recommended mounting pad size



印章代码 / Marking

见印章说明。See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Output Current at $T_c = 125^\circ\text{C}$	I_o	2.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	60	A
Typical Junction Capacitance (Note1)	C_j	40	pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$	70	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55~150	$^\circ\text{C}$

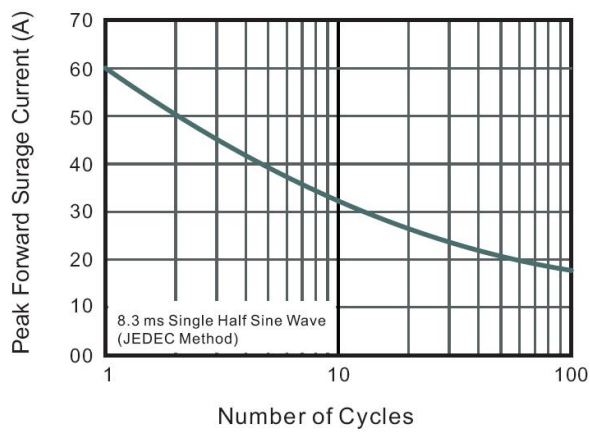
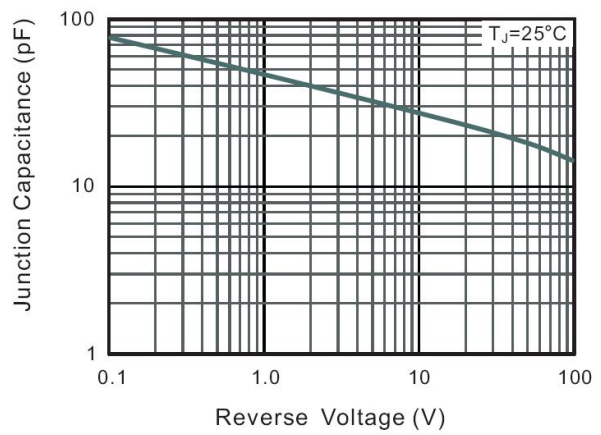
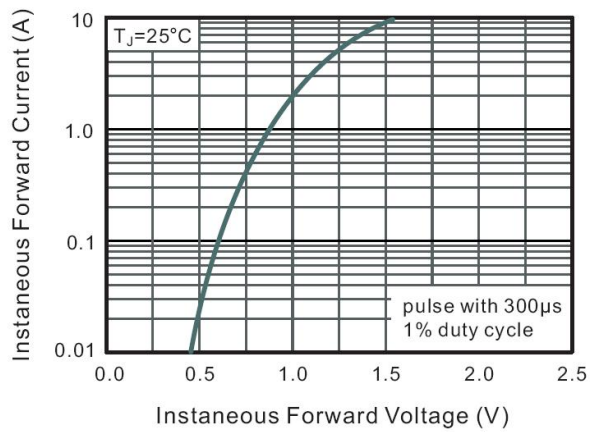
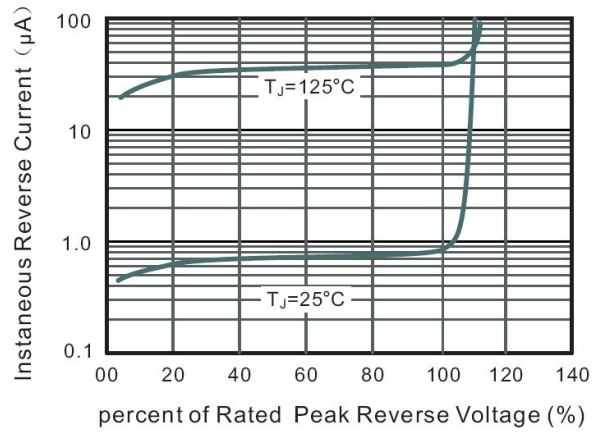
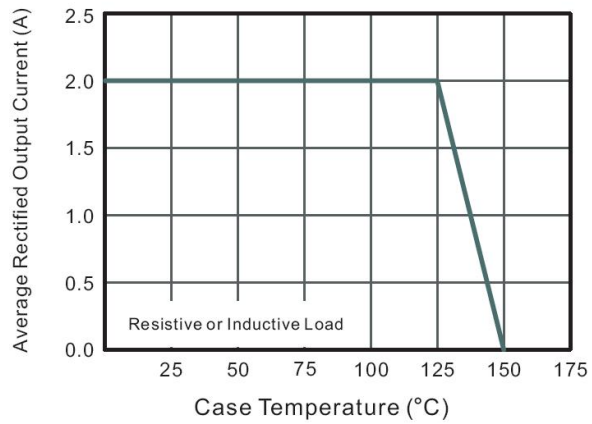
Note:

- 1.Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with $4 \times 1.0'' \times 1.0''$ (2.54 X 2.54 cm) copper pad.

电性能参数 / Electrical Characteristics(Ta=25°C)

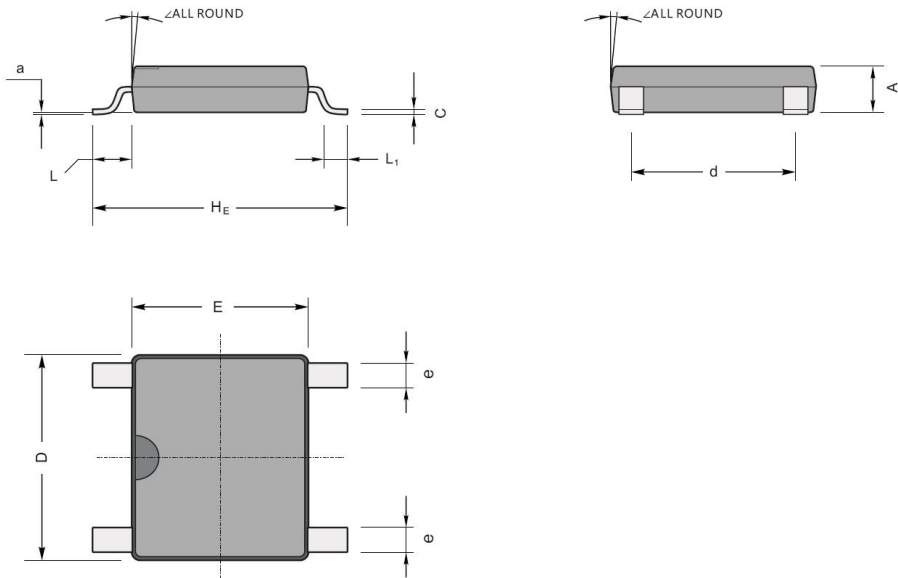
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	V_F	$I_F=2.0\text{A}$	1.3	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25^\circ\text{C}$	5.0	μA
		$T_a=125^\circ\text{C}$	50	μA
Maximum Reverse Recovery Time	t_{rr}	$I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$	200	ns

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

ABF

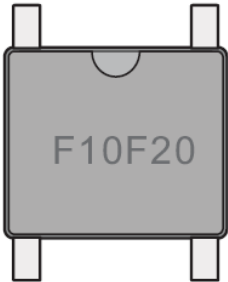


ABF mechanical data

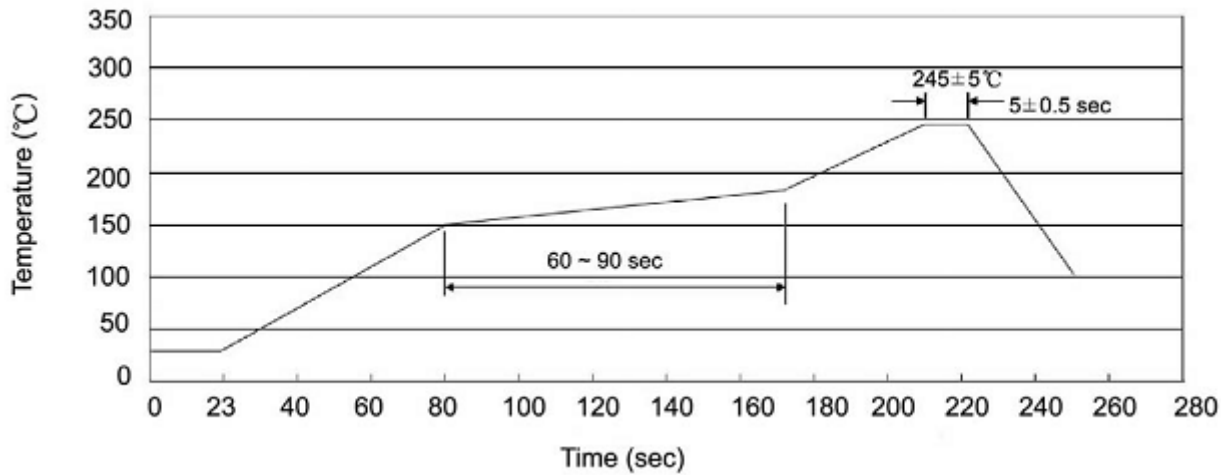
UNIT		A	C	D	E	H _E	d	e	L	L ₁	a	∠
mm	max	1.2	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.0	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	47	8.7	205	177	252	165	28	37	24	8	
	min	39	5.9	193	166	236	150	20				

印章说明 / Marking Instructions

Marking

Type number	Marking code
FTB10F-20	F10F20
	

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



- 说明：

 - 1、预热温度 25 ~ 150℃，时间 60 ~ 90sec;
 - 2、峰值温度 245±5℃，时间持续为 5±0.5sec;
 - 3、焊接制程冷却速度为 2 ~ 10℃/sec.
- Note:

 - 1.Preheating:25~150℃, Time:60~90sec.
 - 2.Peak Temp.:245±5℃, Duration:5±0.5sec.
 3. Cooling Speed: 2~10℃/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec.

Temp.:260±5℃ Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
ABF	5000	2	10000	5	50000	13" ×15	336X336X40	345X345X235

使用说明 / Notices